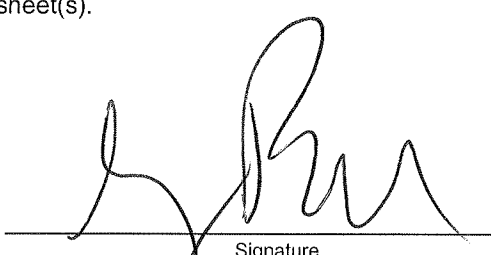


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PRE-APPEAL BRIEF REQUEST FOR REVIEW		Docket Number (Optional) AYUKAWA 1-4-1-162-30	
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		<p>First Named Inventor Seung H. Kang, et al.</p>	
		<p>Art Unit 2814</p>	<p>Examiner Wai Sing Louie</p>
<p>Applicant requests review of the final rejection in the above-identified application. No amendments are being filed with this request.</p> <p>This request is being filed with a notice of appeal.</p> <p>The review is requested for the reason(s) stated on the attached sheet(s). Note: No more than five (5) pages may be provided.</p> <div style="display: flex; justify-content: space-between; align-items: flex-start; margin-top: 20px;"><div style="width: 45%;"><p>I am the</p><p><input type="checkbox"/> applicant/inventor.</p><p><input type="checkbox"/> assignee of record of the entire interest. See 37 CFR 3.71. Statement under 37 CFR 3.73(b) is enclosed. (Form PTO/SB/96)</p><p><input checked="" type="checkbox"/> attorney or agent of record. 44995 Registration number _____</p><p><input type="checkbox"/> attorney or agent acting under 37 CFR 1.34. Registration number if acting under 37 CFR 1.34 _____</p></div><div style="width: 50%; text-align: center;"> _____ Signature Greg H. Parker _____ Typed or printed name 972-480-8800 _____ Telephone number May 23, 2008 _____ Date</div></div> <p>NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.</p>			
<p><input checked="" type="checkbox"/> *Total of <u>1</u> forms are submitted.</p>			

This collection of information is required by 35 U.S.C. 132. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11, 1.14 and 41.6. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Seung H. Kang, *et al.*

Serial No.: 10/675,258

Filed: September 30, 2003

Title: ALUMINUM PAD POWER BUS AND SIGNAL ROUTING FOR
INTEGRATED CIRCUIT DEVICES UTILIZING COPPER
TECHNOLOGY INTERCONNECT STRUCTURES

Grp./A.U.: 2814

Examiner: Thao X. Le

Confirmation No.: 4017

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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May 23, 2008 (Date)

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(Printed or typed name of person signing the certificate)

/Elizabeth Schumacher/
(Signature of the person signing the certificate)

Sir:

PRE-APPEAL BRIEF REQUEST FOR REVIEW

The Applicants have carefully considered this application in connection with the Examiner's Final Rejection mailed January 24, 2008, and respectfully request a pre-appeal brief review of this application in view of the following remarks.

REMARKS/ARGUMENTS

The Applicants previously presented Claims 48-54. Presently, the Applicants have not amended, added or canceled any claims. Accordingly, Claims 48-54 are currently pending in the application.

I. Rejection of Claims 48, 51-53 and 55 under 35 U.S.C. §102

The Examiner has rejected Claims 48, 51-53 and 55 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 6,798,073 to Lin *et al.* ("Lin"). Independent Claim 48 currently includes the elements, among others, of: (1) a metallization interconnect system; (2) a power bus located over the metallization interconnect system; and (3) a passivation layer overlying at least a portion of the power bus. Lin fails to disclose many of these elements.

The Examiner asserts that Lin discloses a metallization interconnect system overlying a substrate **410**, wherein the metallization interconnect system includes a first interconnect feature **422** and second interconnect feature **442** located within a dielectric layer **420** and **440**. Accordingly, features **422** and **442** are first and second interconnect features, and the dielectric layer is **420** and **440** combined. The Examiner then asserts that Lin discloses a power bus **442b** located over the metallization interconnect system, the power bus **442b** comprising an alloy of copper. Thus, according to the Examiner feature **442b** is the power bus. The Examiner then asserts that a passivation layer **440** overlies at least a portion of the power bus **442b**.

The Applicants respectfully assert that the Examiner's interpretation of Lin is incorrect. First, feature **440** is either the dielectric layer, as initially indicated by the Examiner on page 2 of his most recent Examiner's action, or is a passivation layer, as subsequently indicated by the Examiner

on page 3 of his most recent Examiner's action. However, the same feature **440** of Lin cannot be both. Independent Claim 48 includes one element of a dielectric layer, as well as includes another element of a passivation layer. According to the pending claims, these are different layers, thus forming two different features. Therefore, the Examiner cannot use the same feature (e.g., layer **440** of Lin) to anticipate two different features (e.g., the dielectric layer and the passivation layer) of the pending claims.

Second, the Examiner asserts that the metallization interconnect system includes at least a first interconnect feature **422** and a second interconnect feature **442**. Thus, according to the Examiner those two features (e.g., features **422** and **442**) collectively form at least a portion of the metallization interconnect system. The Examiner also asserts that feature **442b** is the power bus. The pending claims, however, require that the power bus be located over the metallization interconnect system. In looking at Lin, however, the power bus feature **442b** is not located over the metallization interconnect system comprising the first interconnect feature **422** and the second interconnect feature **442**. Actually, the power bus feature **442b** is in the same plane as the upper most portion of the metallization interconnect system (e.g., the second interconnect feature **442**) of Lin, as is indicated below. Thus, in direct contrast to what the Examiner asserts, Lin does not disclose a power bus located over the metallization interconnect system, as is presently claimed.

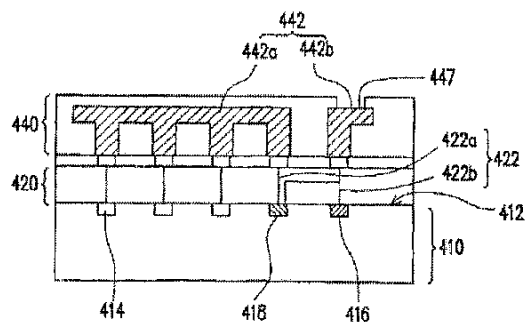


FIG. 4

Third, the Examiner asserts that col. 7, lines 61-63 of Lin teaches that the power bus **442b** comprises an alloy of copper. (See page 3 of the Examiner's Action dated January 24, 2008). The Applicants respectfully disagree. Nowhere in lines 61-63 of col. 7 is there a teaching that the second interconnect scheme **242** (what the Examiner likens to the power bus) comprises an alloy of copper. There appears to be a teaching that it could comprise copper, or aluminum, or gold, or nickel, etc., but such teachings are not that it could comprise an alloy of copper, as is claimed. Accordingly, Lin fails to disclose this element also.

For the foregoing reasons, among others, Lin fails to disclose each and every element of the claimed invention. As such, Lin is not an anticipating reference. Because Claims 49-54 are dependent upon Claim 48, Lin also cannot be an anticipating reference for Claims 49-54. The Applicants therefore respectfully request the Review Panel to withdraw the rejection.

II. Rejection of Claims 49-50 under 35 U.S.C. §103

The Examiner has rejected Claims 49-50 under 35 U.S.C. §103(a) as being unpatentable over Lin. As established above, Lin fails to disclose many of the elements of independent Claim 48.

Lin further fails to suggest such elements. Thus, Lin fails to teach or suggest the invention recited in independent Claim 48 and its dependent claims, when considered as a whole. Therefore, Lin fails to establish a prima facie case of obviousness with respect to these claims. Claims 49-50 are therefore not obvious in view of Lin. The Applicants therefore respectfully request the Review Panel to withdraw the rejection.

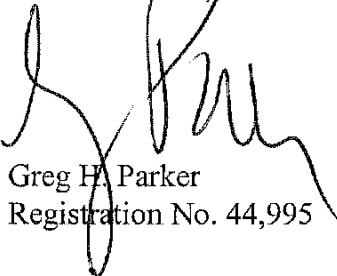
III. Conclusion

In view of the foregoing remarks, the Applicants now see all of the Claims currently pending in this application to be in condition for allowance and therefore earnestly solicit a Notice of Allowance for Claims 48-54.

The Applicants request the Reviewers to telephone the undersigned attorney of record at (972) 480-8800 if such would further or expedite the prosecution of the present application.

Respectfully submitted,

HITT GAINES, PC

A handwritten signature in black ink, appearing to read 'Greg H. Parker', written over the printed name and registration number.

Greg H. Parker
Registration No. 44,995

Dated: May 23, 2008

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